AMENDMENT TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims in the application and reflects amendments over the most recent version of the claims. A clean version of the claims is provided with the substitute specification filed herewith at Tab A.

Listing of Claims

1. (Currently Amended) An integrated read-only memory, comprising having a plurality of selection transistors each having a drain connection, having an electrode for feeding a voltage or a current;

having a layer between the <u>each</u> drain connections and the electrode, <u>having a modifiable</u> the electrical resistance of which can be changed through the effect of a configuration voltage or a configuration current electrical signal,

having-a source connection per selection transistor;

having a bit line that is electrically connected to at least one source connection:

in which where the layer is formed as a common layer for linking the drain connections to the electrode, and

in which where the electrical resistance of the layer can be changed locally.

- 2. (Currently Amended) The read-only memory as claimed in of claim 1, in which where the resistance of the layer can be switched over.
- 3. (Currently Amended) The read-only memory as claimed in of claim 1 or 2, in which where the resistance of the layer can be switched over between two multiple resistance characteristic curves.

Appl. No.: To Be Assigned

Preliminary Amdt. Dated August 20, 2004

4. (Currently Amended) The read-only memory as claimed in one of the preceding of claims 1, comprising:

having a read voltage signal applied to the layer or a read current fed to the layer within a defined voltage or current signal range in a read operation of the read-only memory, and

having a configuration voltage or a configuration current signal outside the voltage or current-read signal range provided for the read operation in a configuration operation of the read-only memory.

- 5. (Currently Amended) The read-only memory as claimed in one of the preceding of claim 1s, which where the read-only memory is designed as a flash memory.
- 6. (Currently Amended) The read-only memory as claimed in one of the preceding of claims 1, in which where the selection transistors are arranged in an array.
- 7. (Currently Amended) The read-only memory as claimed in one of claims-1-to-6, in which where the bit line is connected to a decoder circuit.
- 8. (Currently Amended) The read-only memory as claimed in one of claims 1-to 7, in which where the bit line is accessible for an external connection.
- 9. (Currently Amended) The read-only memory as claimed in one of the preceding of claims 1, comprising:

having-a gate connection per selection transistor; and having-a word line that is being electrically connected to at least one gate connection.

- 10. (Currently Amended) The read-only memory as claimed in of claim 9, in which where the word line is connected to a decoder circuit.
- 11. (Currently Amended) The read-only memory as claimed in of claim 9 or claim 10, in which where the word line is accessible for an external connection.

Appl. No.: To Be Assigned

Preliminary Amdt. Dated August 20, 2004

- 12. (Currently Amended) The read-only memory as claimed in one of the preceding of claims 9, in which where the selection transistors have a substantially planar construction in the substrate.
- 13. (Currently Amended) The read-only memory as claimed in one of of claims 1-to 11, in which where the selection transistors have a vertical construction in the substrate.
- 14. (Currently Amended) The read-only memory as claimed in one of the preceding of claims 1, in which where the layer is formed as a molecular layer.
- 15. (Currently Amended) The read-only memory as claimed in of claim 14, in which where the layer contains rotaxane.
- 16. (Currently Amended) The read-only memory as claimed in of claim 14, in which where the layer contains catenane.
- 17. (Currently Amended) The read-only memory as claimed in of claim 14, in which where the layer contains a bispyridinium compound.
- 18. (Currently Amended) The read-only memory as claimed in one of claims-1-to 13, in which where the layer is formed as a dielectric.
- 19. (Currently Amended) The read-only memory as claimed in of claim 18, in which where the layer contains SrZrO₃.
- 20. (Currently Amended) The read-only memory as claimed in one of claims 1-to 13, in which where the layer is formed as a polymer.
- 21. (Currently Amended) The read-only memory as claimed in of claim 20, in which where the layer contains 3-nitrobenzal malonitrile, 1,4-phenylenediamine complex.
- 22. (Currently Amended) The read-only memory as claimed in of claim 20, in which where the layer contains a chalcogenide compound.

23. (Currently Amended) A method for operating an integrated read-only memory having a plurality of selection transistors each having a drain connection and an electrode for feeding a voltage or a current, including a layer between each drain connection and the electrode, as claimed in one of the preceding claims, comprising:

providing a layer between each drain connection and the electrode, they layer having a modifiable electrical resistance through a configuration electrical signal, where the layer is formed as a common layer for linking the drain connections to the electrode, and where the electrical resistance of the layer can be changed locally;

applying in which in a read operation, a read voltage or a read current within a defined voltage or current range is applied to the layer; and

applying in which, in a configuration operation, a configuration voltage or a configuration current outside the voltage or current range provided for the read operation is applied to the layer.

24. (Currently Amended) A method for producing an integrated read-only memory, comprising:

in which producing an array of selection transistors is produced using CMOS technology;

in which leading drain contacts of the selection transistors are led-to the surface of the arrangement;

in which depositing a layer is deposited whose having an electrical resistance that can be changed through the effect of a configuration voltage or a configuration current signal, it being possible for where the electrical resistance of the layer to may be changed locally;

in which arranging an electrode is arranged above the layer;

in which forming a source connection is formed per selection transistor;

in which forming a bit line is formed which is electrically connected to at least one source connection; and

in which forming the layer is formed as a common layer for linking the drain connections to the electrode.

- 25. (Currently Amended) The method for producing an integrated read-only memory as elaimed in of claim 24, in which where the layer is deposited as a common layer for linking the drain connections to the electrode above the selection transistors.
- 26. (Currently Amended) The method for producing an integrated read-only memory as claimed in of claim 24 or claim 25, in which where the selection transistors are produced in a front end process.
- 27. (Currently Amended) The method for producing an integrated read-only memory as elaimed in one of claims 24-to 26, in which where the layer is deposited in a back end process.
- 28. (Currently Amended) The method for producing an integrated read-only memory as elaimed in one of claims 24 to 27, in which where the selection transistors are constructed in substantially planar fashion in the substrate.
- 29. (Currently Amended) The method for producing an integrated read-only memory as elaimed in one of claims 24 to 27, in which where the selection transistors are constructed vertically in the substrate.
- 30. (Currently Amended) The method for producing an integrated read-only memory as claimed in one of claims 24 to 29, in which where the layer is formed as a molecular layer.
- 31. (Currently Amended) The method for producing an integrated read-only memory as claimed in-of claim 30, in which where the layer contains rotaxane.
- 32. (Currently Amended) The method for producing an integrated read-only memory as claimed in of claim 30, in which where the layer contains catenane.
- 33. (Currently Amended) The method for producing an integrated read-only memory as elaimed in of claim 30, in which where the layer contains a bispyridinium compound.

Appl. No.: To Be Assigned

Preliminary Amdt. Dated August 20, 2004

34. (Currently Amended) The method for producing an integrated read-only memory as elaimed in one of claims 24 to 29, in which where the layer is formed as a dielectric.

- 35. (Currently Amended) The method for producing an integrated read-only memory as elaimed in of claim 34, in which where the layer contains SrZrO₃.
- 36. (Currently Amended) The method for producing an integrated read-only memory as elaimed in one of claims 24 to 29, in which where the layer is formed as a polymer.
- 37. (Currently Amended) The method for producing an integrated read-only memory as elaimed of in-claim 36, in-which where the layer contains a 3-nitrobenzal malonitrile, 1,4-phenylenediamine complex.
- 38. (Currently Amended) The method for producing an integrated read-only memory as claimed in one of claims 24 to 29, in which where the layer contains a chalcogenide compound.